



□



T<sub>C</sub> =25

Parameter	Symbol	Rating	Unit
Drain-Source Voltage			

**Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	-	15	° C/W
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	120	° C/W
Soldering temperature, wavesoldering for 10s	$T_{sold}$	-	-	265	° C

□

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	60			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.2		2.5	V

Fig.1 Gate-Charge Characteristics

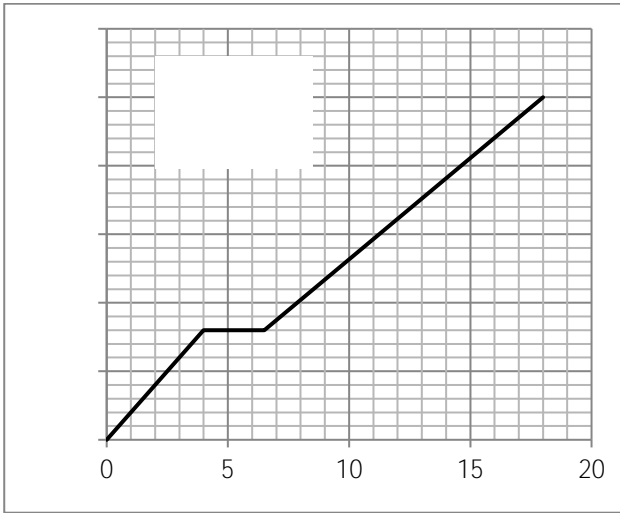


Fig.2 Capacitance Characteristics

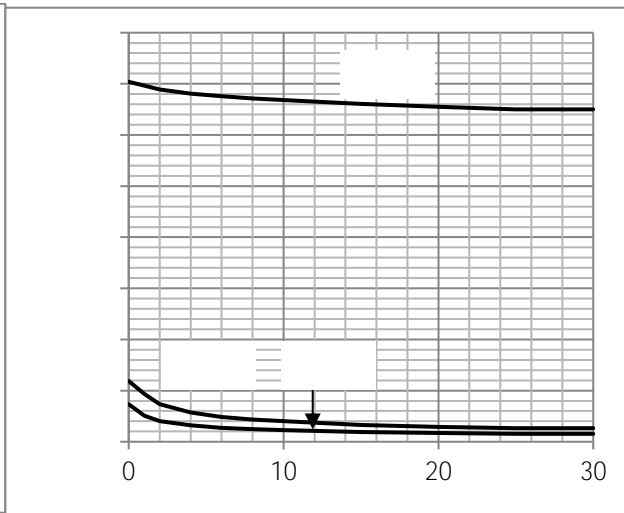


Fig.3 Power Dissipation Derating Curve

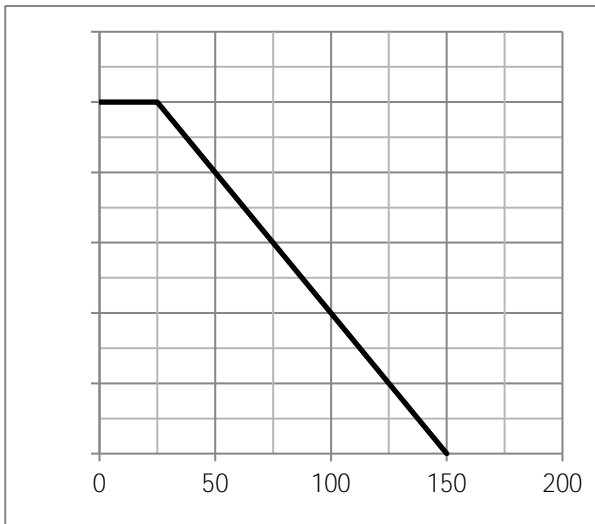


Fig.2 Typical output Characteristics

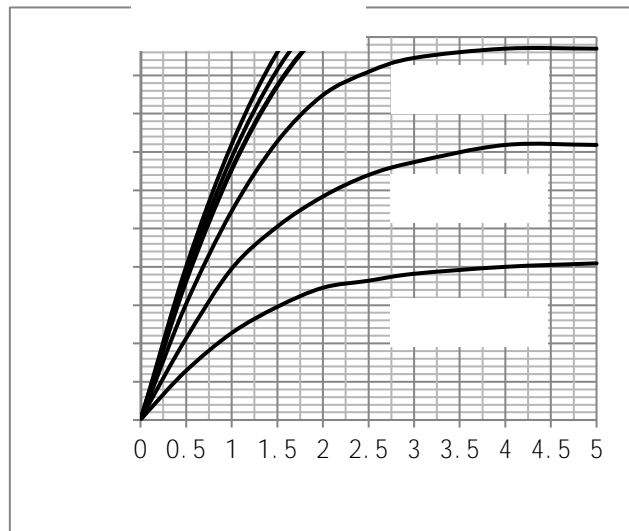


Fig.3 Threshold Voltage V.S Junction Temperature

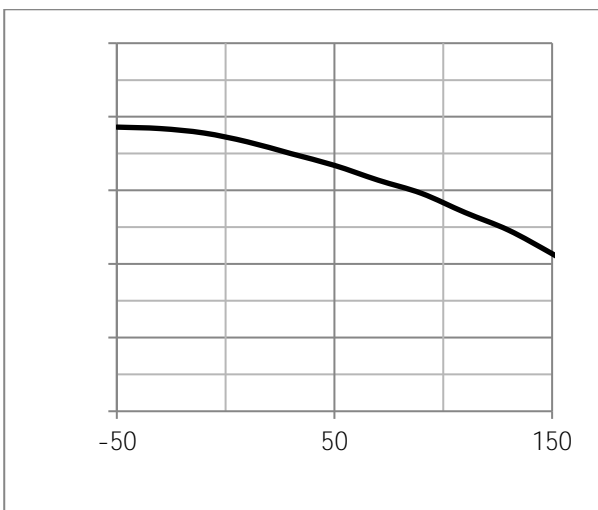
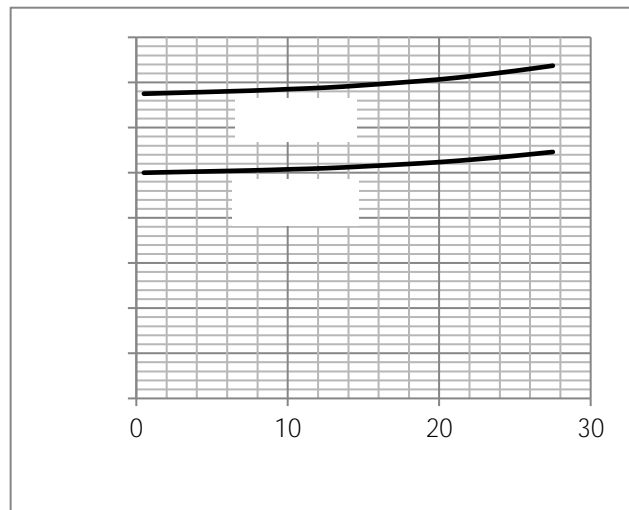


Fig.4 Resistance V.S Drain Current



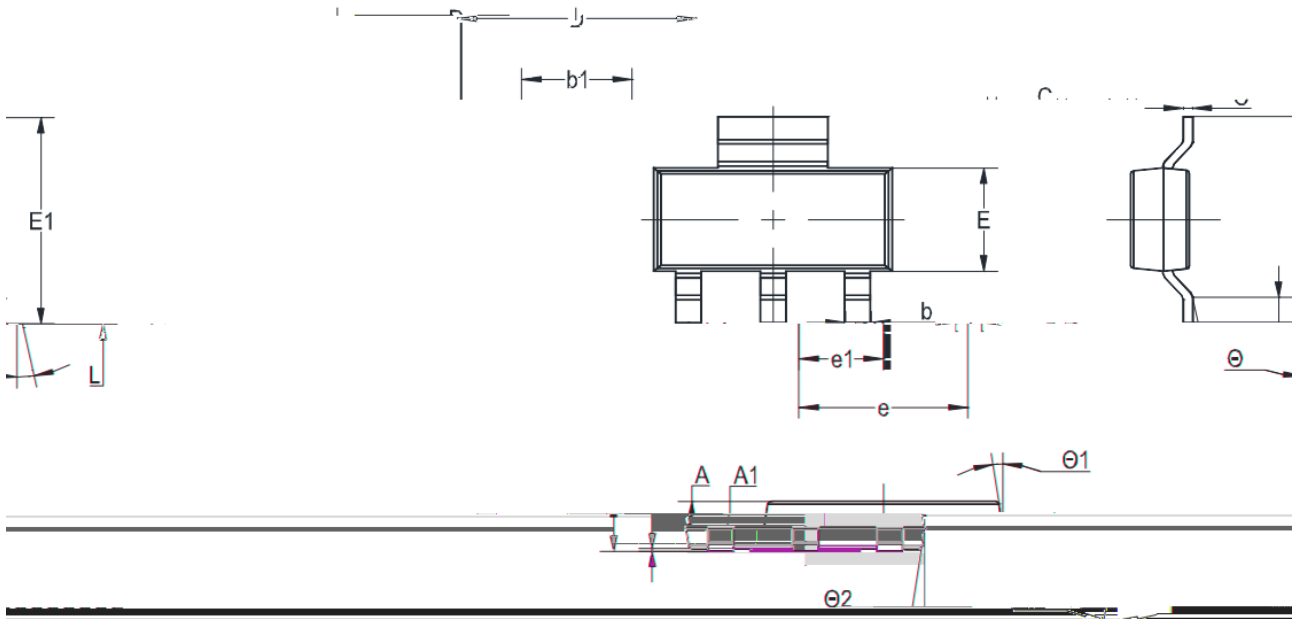
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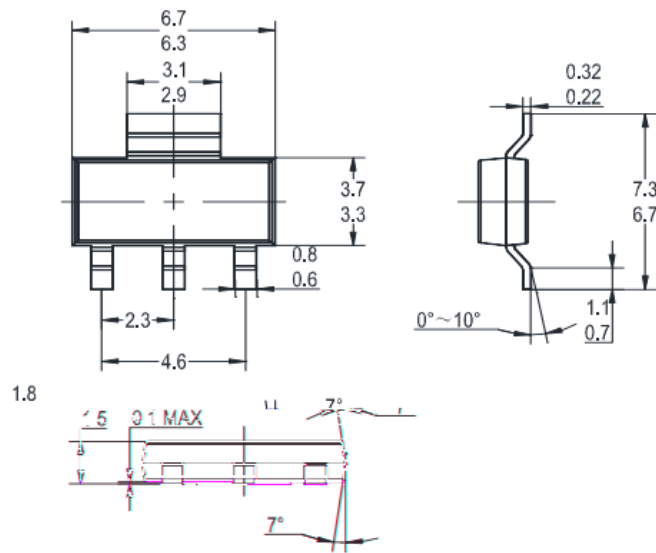


(SOT-223)

Unit mm

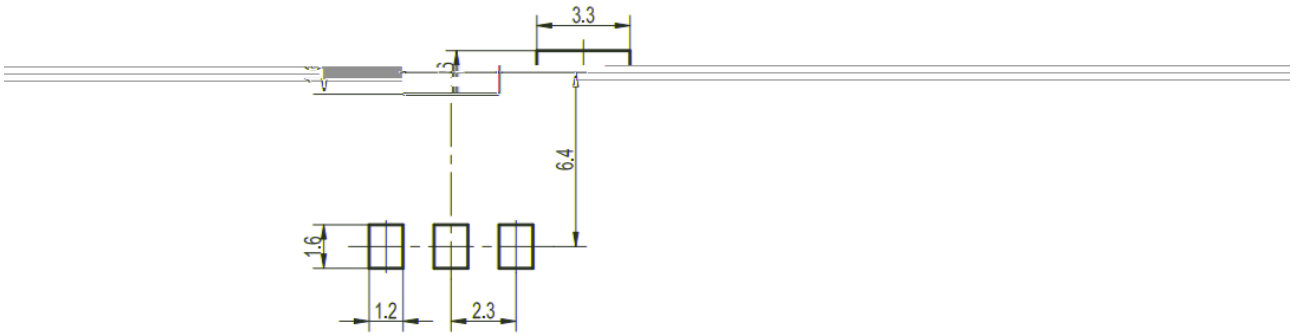


a	a1	L	θ	θ1	θ2	Unit	A	A1	b	b1	C	D	E	E1
3.7	7.3	4.6	2.3	1.1	10°	mm			1.8	0.1	0.8	3.1	0.32	6.7
3.3	6.7	TYP	TYP	0.7	0°				1.5	MAX	0.6	2.9	0.22	6.3





**Recommended Soldering Footprint**



**Shipping information**

Unit	mm	Unit	Packaging Quantity	Package	Lead Width (mm)	Lead Pitch (mm)	Part No.
315 ± 0.004	330	13	3,000	SOT-223	12	8 ± 0.1	0.